

**Product Summary**

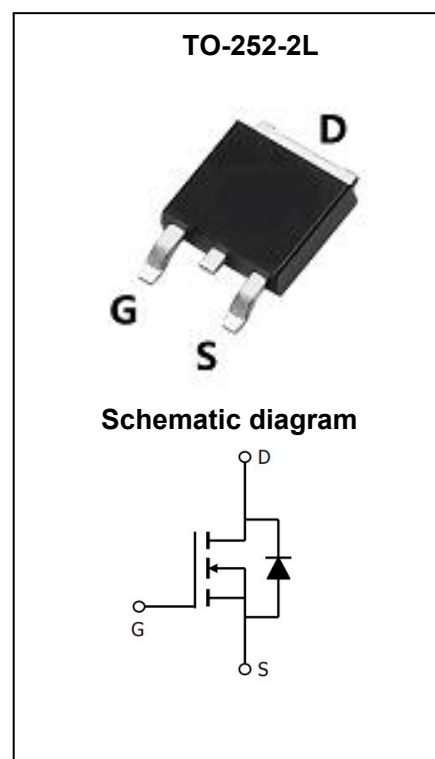
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
700V	950m $\Omega$ @10V	5A

**Feature**

- Super-Junction MOSFET
- High Ruggedness
- Low RDS(ON)
- 100% Avalanche Tested
- Improved dv/dt Capability

**Application**

- Charger
- PC Power
- LED Lighting


**Package Marking and Ordering Information**

Part Number	Package	Marking	Packing	Reel Size	Tape Width	Qty
GPJ70R950TF	TO-252-2L	J70R950	Tape&Reel	330mm	16mm	2500pcs

**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	700	V
Gate - Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ\text{C}$	$I_D$	5
	$T_C = 100^\circ\text{C}$	$I_D$	3.2
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	15	A
Single Pulsed Avalanche Energy <sup>3</sup>	$E_{AS}$	65	mJ
Repetitive Avalanche Energy <sup>2</sup>	$E_{AR}$	6	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	$P_D$	65.8
MOSFET dv/dt Ruggedness( $V_{DS}=0\sim 480\text{V}$ )	dv/dt	50	V/ns
Peak Diode Recovery dv/dt( $V_{DS}=0\sim 400\text{V}$ , $I_{SD}\leq I_D$ )	dv/dt	15	V/ns
Thermal Resistance, Junction to Case	$R_{thjc}$	1.9	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient	$R_{thja}$	62	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	-55~ +150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

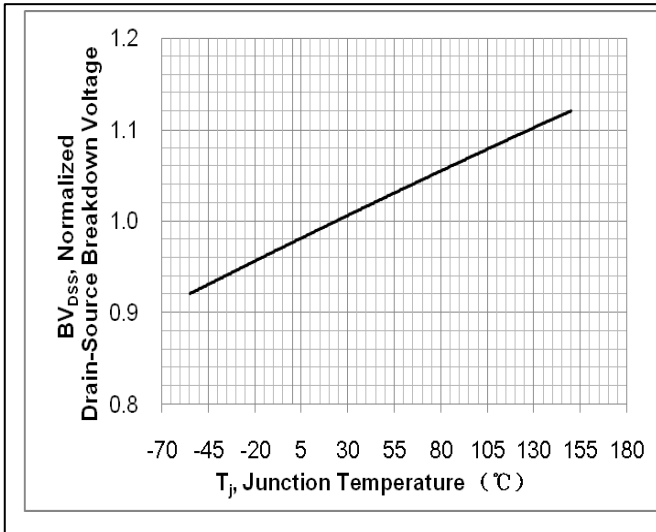
## MOSFET ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	700			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D = 250\mu A$ , referenced to $25^\circ\text{C}$		0.66		$V/^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 700V, V_{GS} = 0V$			1	$\mu A$
		$V_{DS} = 560V, T_J = 125^\circ\text{C}$			50	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.8	3.3	3.8	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 2.5A$		790	950	$m\Omega$
Forward Transconductance	$G_{fs}$	$V_{GS} = 30V, I_D = 2.5A$		4.4		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 200V, V_{GS} = 0V, f = 1\text{MHz}$		311		pF
Output Capacitance	$C_{oss}$			22		
Reverse Transfer Capacitance	$C_{rss}$			1.1		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$		13		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 560V, V_{GS} = 10V, I_D = 5A$		14.8		nC
Gate-Source Charge	$Q_{gs}$			4.1		
Gate-Drain Charge	$Q_{gd}$			3.9		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = 350V, V_{GS} = 10V, I_D = 5A, R_G = 10\Omega$		11		ns
Turn-On Rise Time	$t_r$			23		
Turn-Off Delay Time	$t_{d(off)}$			21		
Turn-Off Fall Time	$t_f$			23		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0V, I_S = 5A$			1.4	V
Diode Continuous Forward Current	$I_S$	Integral reverse p-n Junction diode in the MOSFET			5	A
Body Diode Reverse Recovery Time	$t_{rr}$	$I_S = 5A, di/dt = 100 A/\mu s, V_{GS} = 0V$		217		ns
Body Diode Reverse Recovery Charge	$Q_{rr}$				1.6	

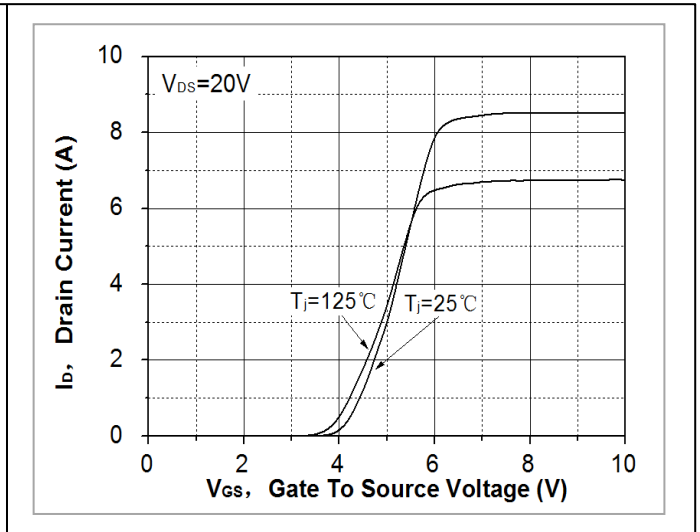
Notes :

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3.  $L = 40mH, I_{AS} = 4.5A, V_{DD} = 100V, R_G = 25\Omega$ , Starting at  $T_J = 25^\circ\text{C}$ .

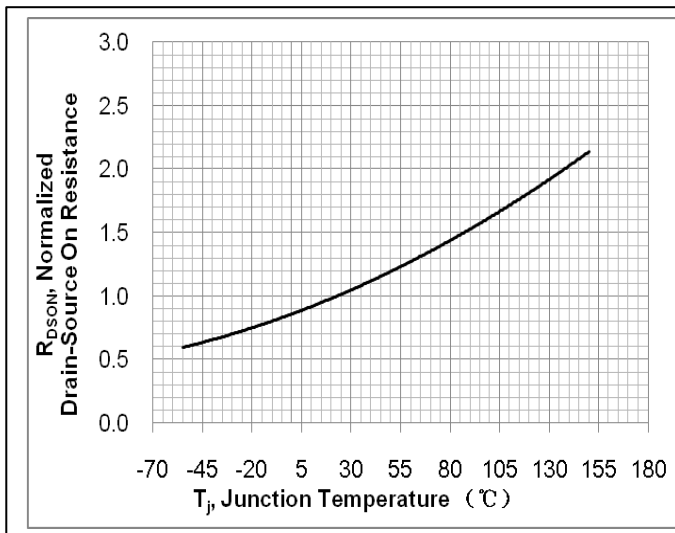
**Typical Characteristics**



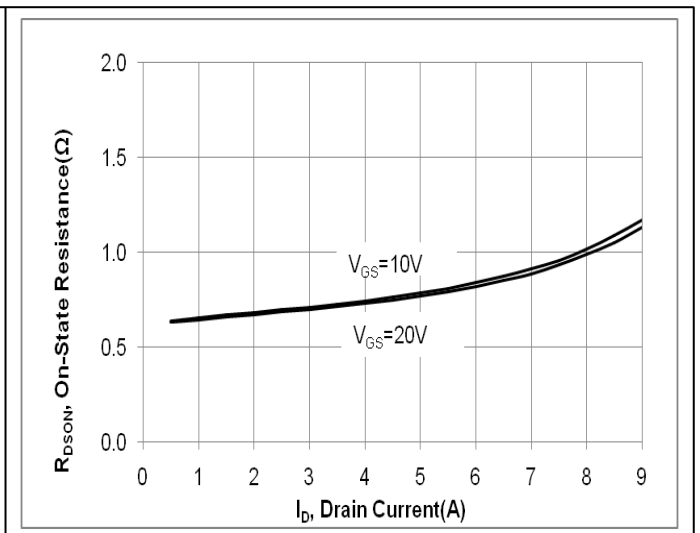
**Fig1.  $BV_{DSS}$  vs Junction Temperature**



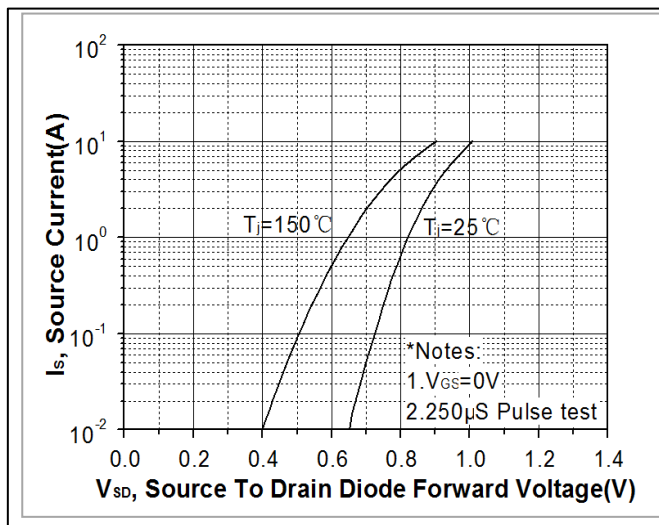
**Fig 2. Transfer characteristics**



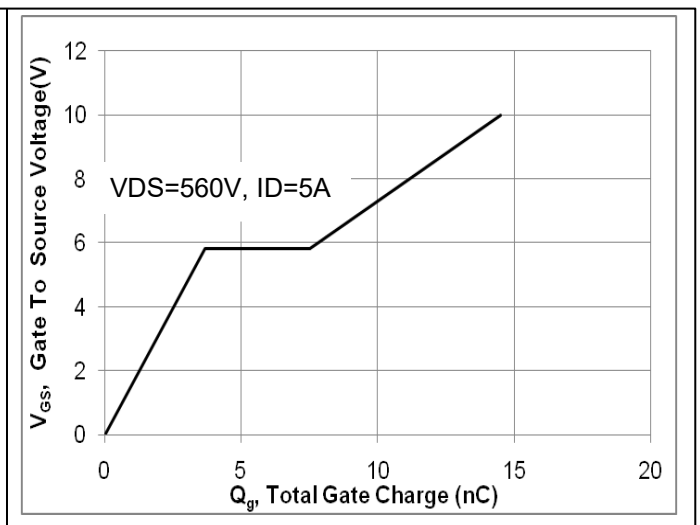
**Fig 3.  $R_{DS(ON)}$  vs Junction Temperature**



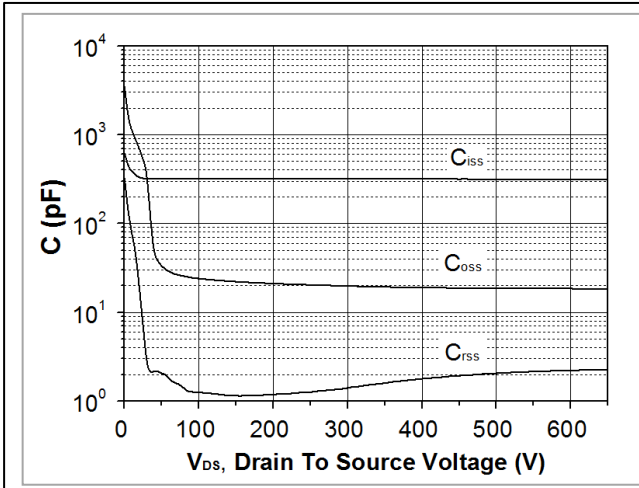
**Fig 4. Drain-source on-state resistance**



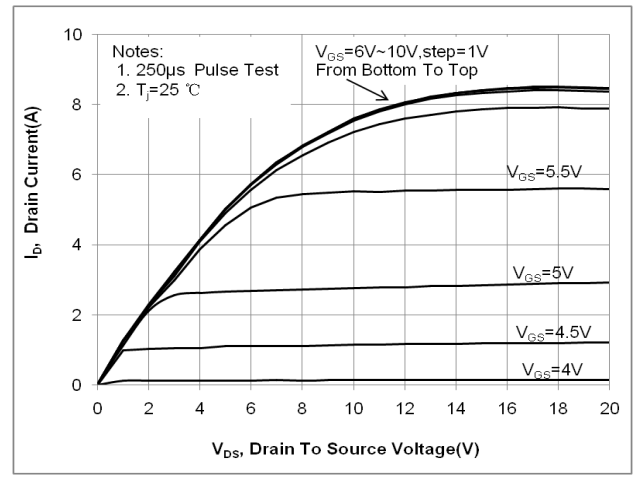
**Fig 5 . Forward characteristics of reverse diode**



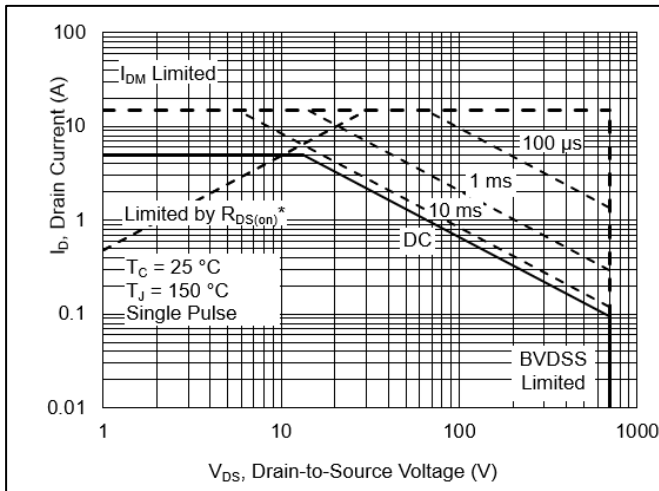
**Fig 6. Gate charge characteristics**



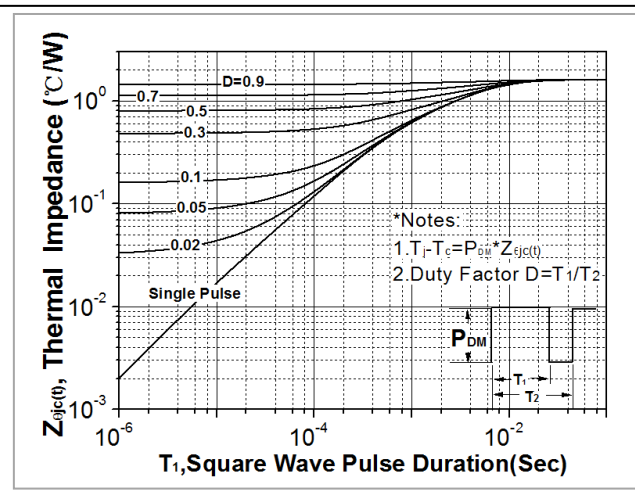
**Fig 7. Capacitance Characteristics**



**Fig 8. Output characteristics (T<sub>J</sub>=25 °C)**

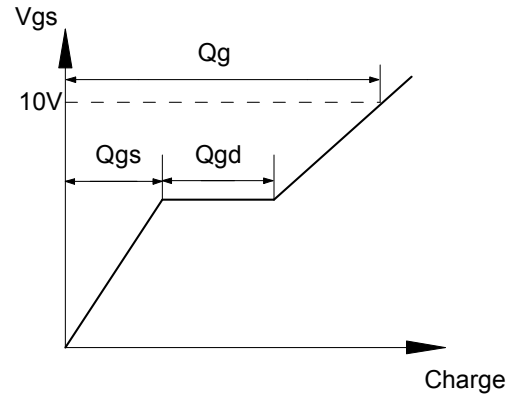
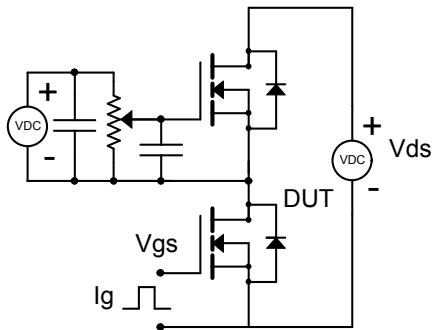


**Fig 9. Safe operating area(TO-252)**

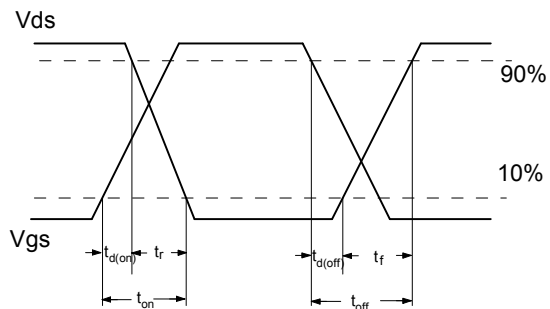
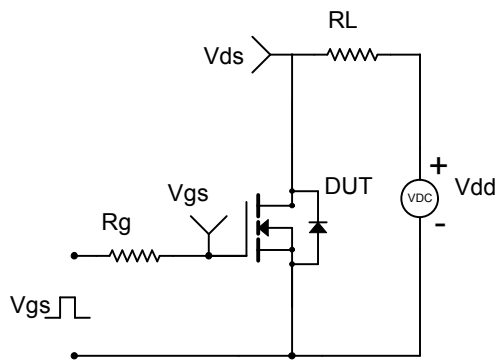


**Fig 10. Transient thermal impedance (TO-252)**

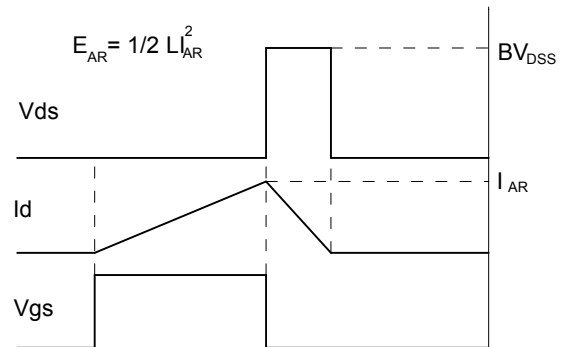
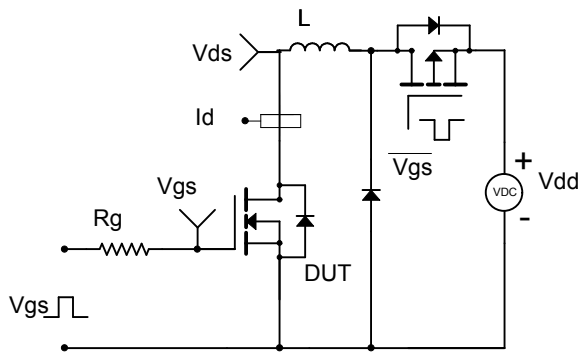
Gate Charge Test Circuit & Waveform



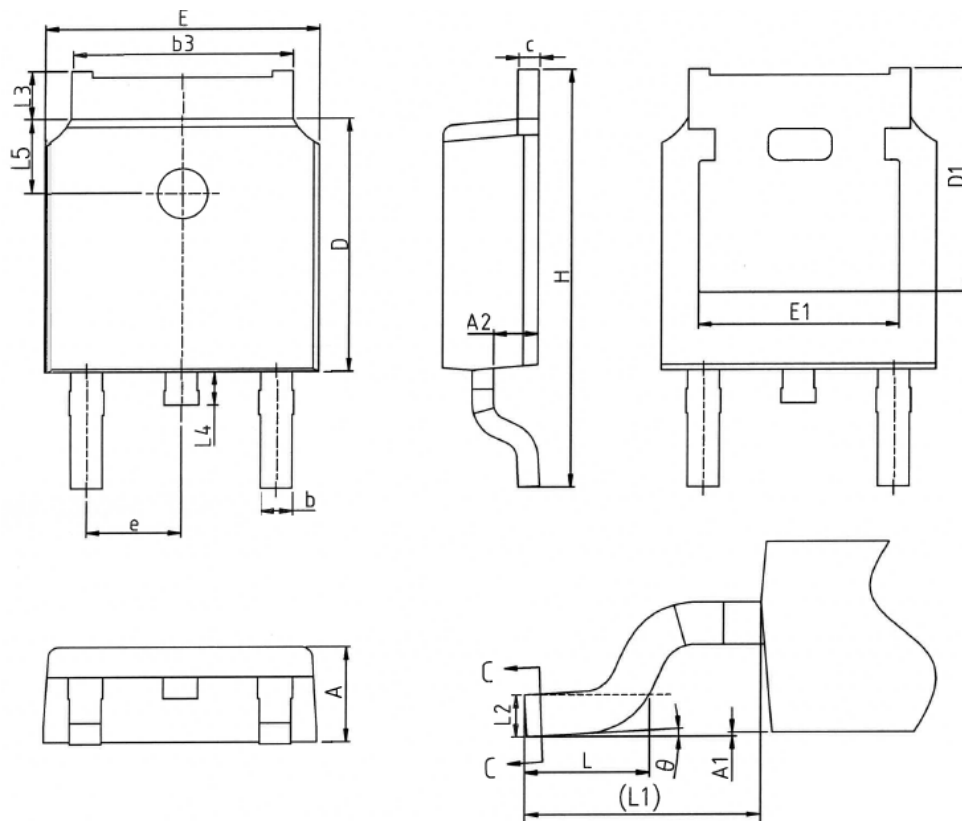
Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



## TO-252-2L Package Information



NOTES  
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 AA,  
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°

**Attention:**

- GreenPower Electronics reserves the right to improve product design function and reliability without notice.
- Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.
- GreenPower Electronics products belong to consumer electronics or other civilian electronic products.